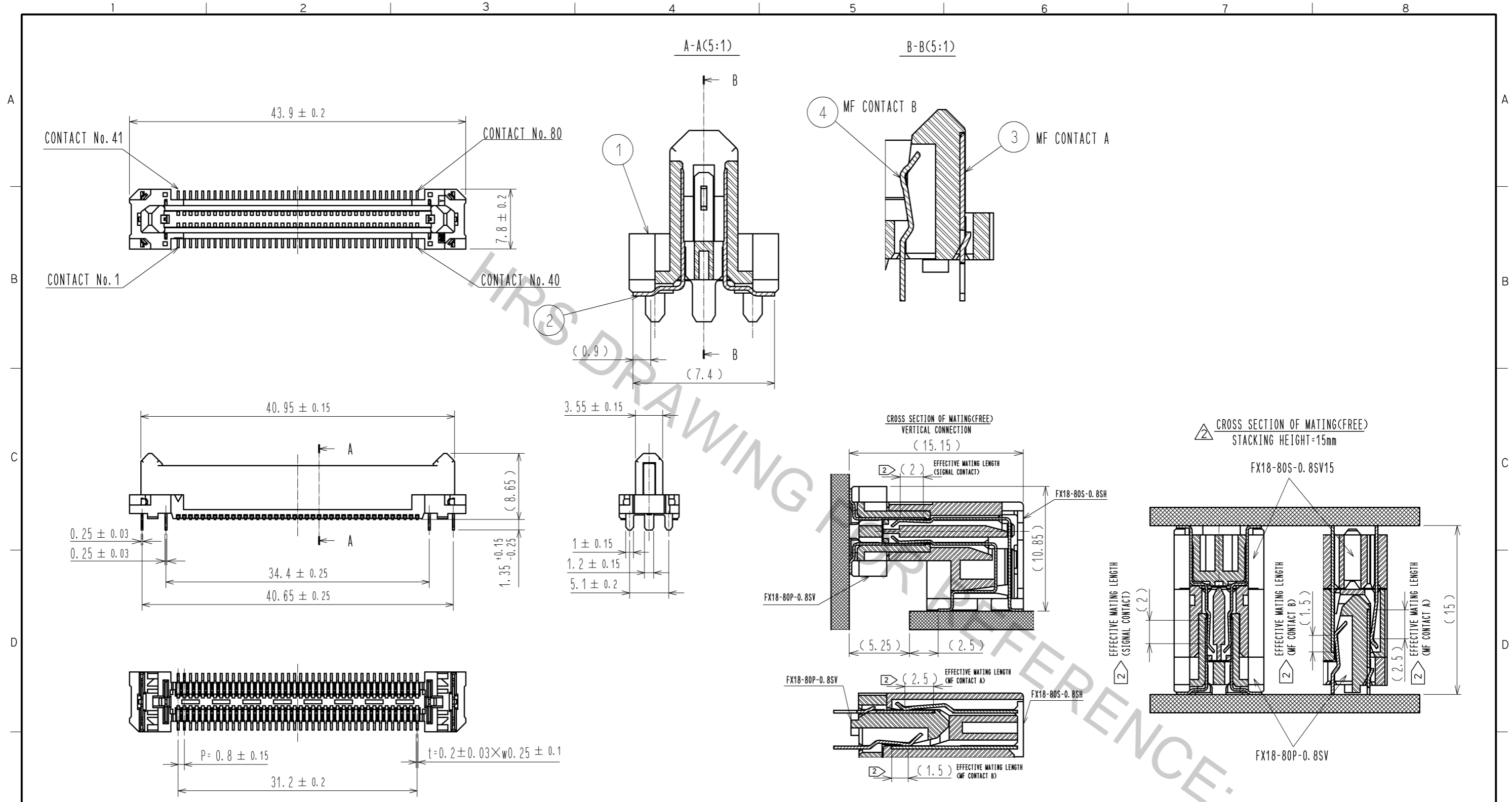


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NOTE 1 LEAD CO-PLANARITY IS 0.1mm MAX.
 ② CONTACTS ARE 3 STEPS SEQUENTIAL. (MF CONTACT A=>SIGNAL CONTACT=>MF CONTACT B)
 WHEN USING THIS SEQUENTIAL STRUCTURE, PLEASE AVOID ANGLED INSERTION.
 3 MF CONTACT A AND MF CONTACT B CAN BE USED AS POWER SUPPLY CONTACT. (3A/PIN MAX)
 ④ IT SHOWS THE VACUUM PICKUP AREA. (SEE PAGE 2)
 REMOVE THE MYLAR TAPE BEFORE MATING CONNECTORS.
 ⑤ THIS IS PACKAGED IN TRAY. (50pcs/TRAY)
 6 BLEMISH AND HIT MARK CAN BE OCCURED THROUGH OUT THE MANUFACTURING PROCESS WHICH DOESN' T AFFECT QUALITY LEVEL.
 7 THE DIMENSIONS IN PARENTHESES ARE FOR REFERENCES.

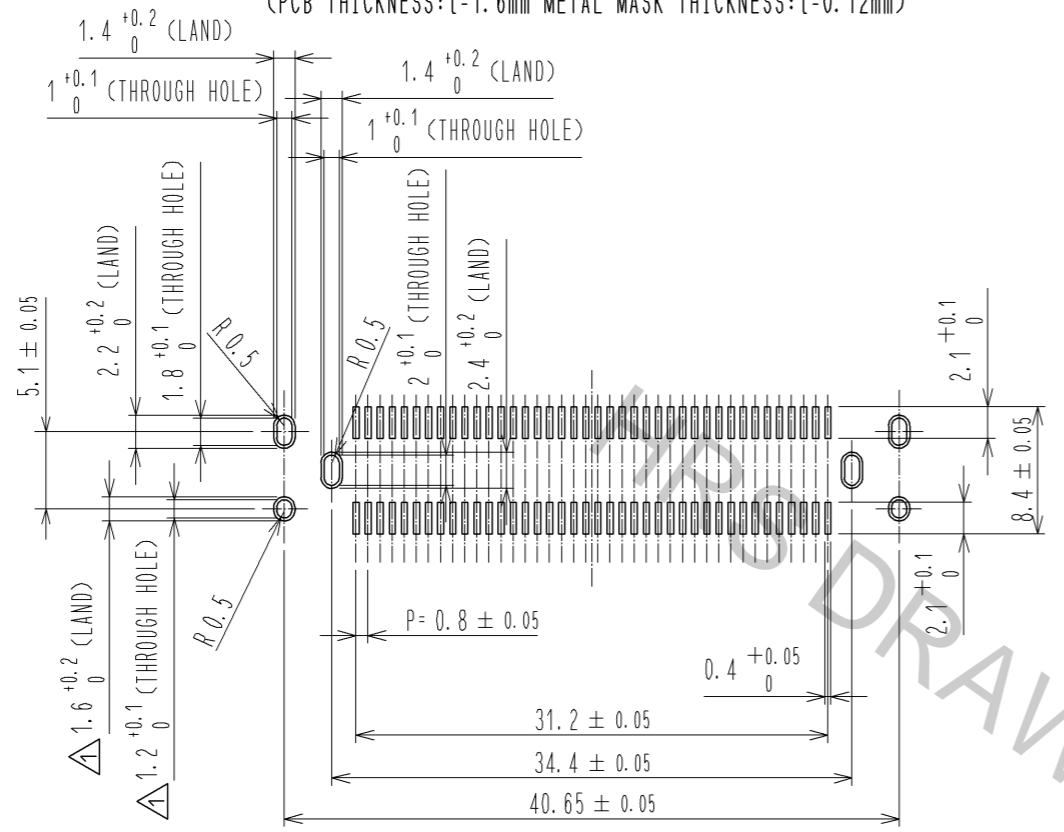
3	PHOSPHOR BRONZE	CONTACT AREA:GOLD 0.1 μm			
		LEAD AREA:TIN-PLATING 1 μm			
2	PHOSPHOR BRONZE	UNDER PLATING:NICKEL 1.3 μm	6	POLYIMIDE	
		CONTACT AREA:GOLD 0.1 μm	5	POLYSTYRENE	
1	POLYAMIDE	LEAD AREA:GOLD 0.03 μm	4	PHOSPHOR BRONZE	CONTACT AREA:GOLD 0.1 μm
		UNDER PLATING:NICKEL 1.3 μm			LEAD AREA:TIN-PLATING 1 μm
NO.	MATERIAL	FINISH . REMARKS	NO.	MATERIAL	FINISH . REMARKS
1	POLYAMIDE	BLACK UL94V-0	1	PHOSPHOR BRONZE	UNDER PLATING:NICKEL 1.3 μm

UNITS mm		SCALE 2 : 1	COUNT 1	DESCRIPTION OF REVISIONS DIS-F-005993	DESIGNED TH. SANO	CHECKED KI. HIROKAWA	DATE 12.01.27
HRS HIROSE ELECTRIC CO., LTD.		APPROVED : HS. OKAWA	10.06.16	DRAWING NO.	EDC3-159562-00		
		CHECKED : KI. HIROKAWA	10.06.16	PART NO.	FX18-80P-0.8SV		
		DESIGNED : TH. SANO	10.06.16	CODE NO.	CL579-0018-5-00		
		DRAWN : TH. SANO	10.06.16		② 1/2		

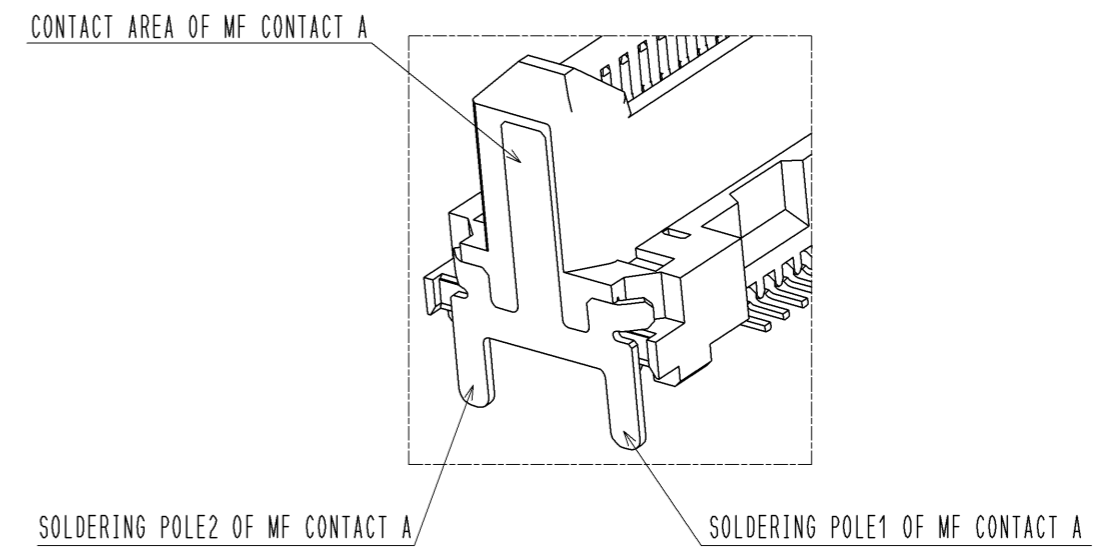
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1 2 3 4 5 6 7 8

RECOMMENDED LAND PATTERN DIMENSION OF PCB(2:1)
(PCB THICKNESS:t=1.6mm METAL MASK THICKNESS:t=0.12mm)

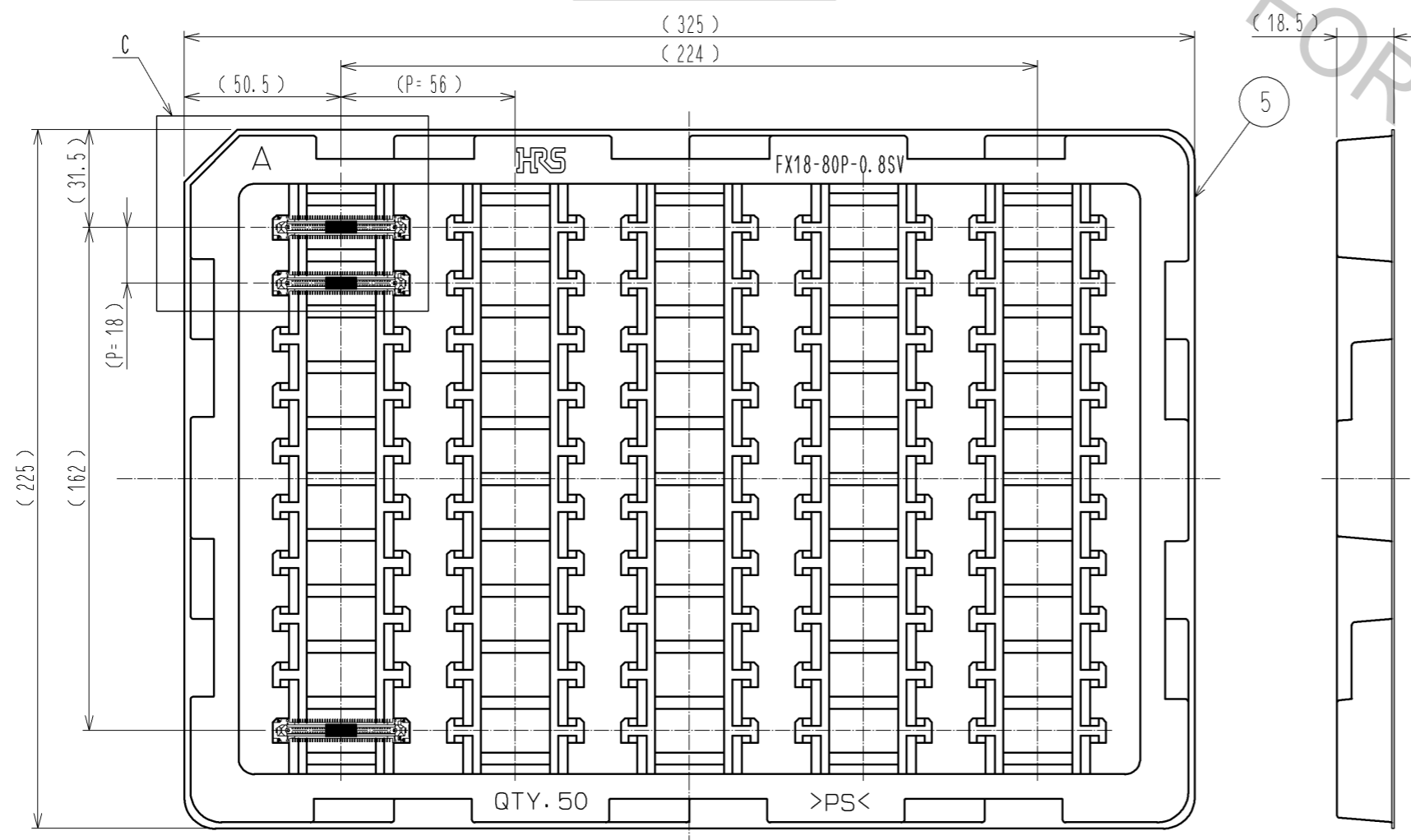


8 CONFIGURATION OF MF CONTACT A

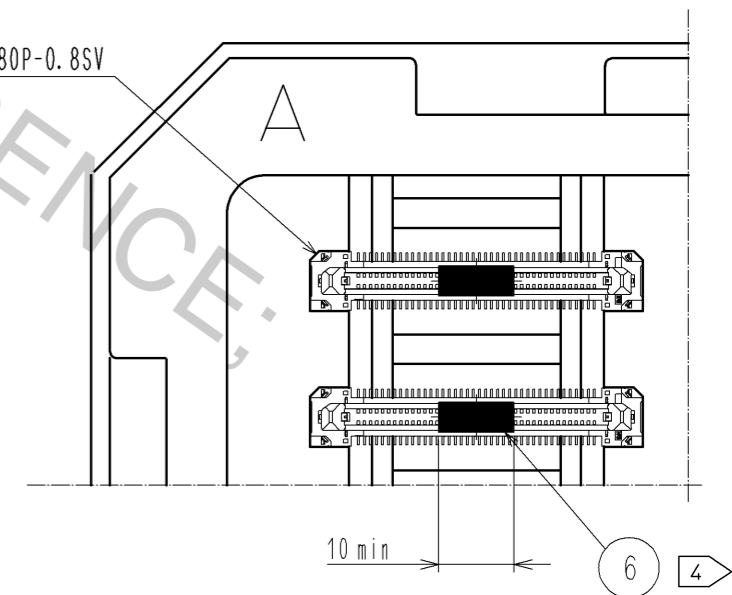


NOTE 8 SOLDERING LEAD OF MF CONTACT A SPLITS INTO TWO POLES.
BE SURE TO CONNECT TO THE SAME CIRCUIT.

5 DRAWING FOR PACKING(1:2)



C(1:1)



HRS	DRAWING NO.	EDC3-159562-00	2/2
	PART NO.	FX18-80P-0.8SV	
	CODE NO.	CL579-0018-5-00	